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DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **PROCESS OF FORMING METAL SURFACES COMPATIBLE WITH A WIRE BONDING AND SEMICONDUCTOR INTEGRATED CIRCUITS MANUFACTURED BY THE PROCESS**; the specification of which is attached hereto;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application listed below.

Prior U.S.A. Application

Application No.: 60/269,500

Filing Date: February 16, 2001

Status: Pending

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: Vaidyanathan Kripesh

Inventor's signature

V. Kripesh

Date

14/02/02

Residence: Blk 428, #10-434, Clementi Avenue 3, Singapore 120428

Citizenship: Indian

Post Office Address: Same as Residence

Full name of second inventor: Mahadevan K. Iyer

Inventor's signature Mahadevan K. Iyer

Date 14 February 2002

Residence: Blk 723, #24-180, Clementi West Street 2, Singapore 120723

Citizenship: Indian

Post Office Address: Same as Residence

Full name of third inventor: Thiam Beng Lim

Inventor's signature Thiam Beng Lim

Date 18th February 2002

Residence: 46 Toh Crescent, Singapore 507957

Citizenship: Singaporean

Post Office Address: Same as Residence

Send Correspondence To:

KNOBBE, MARTENS, OLSON & BEAR, LLP

Customer No. 20,995



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ALLEN4.001AUS

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Vaidyanathan et al.)
App. No. : 10/078,243)
Filed : February 14, 2002)
For : PROCESS OF FORMING METAL)
SURFACES COMPATIBLE WITH A)
WIRE BONDING AND)
SEMICONDUCTOR INTEGRATED)
CIRCUITS MANUFACTURED BY)
THE PROCESS)
Examiner : Unknown)

ESTABLISHMENT OF RIGHT OF ASSIGNEE TO TAKE ACTION
AND
REVOCATION AND POWER OF ATTORNEY

United States Patent and Trademark Office
PO Box 2327
Arlington, VA 22202

Dear Sir:

The undersigned is empowered to act on behalf of the assignee below (the "Assignee"). A true copy of the original Assignment of the above-captioned application from the inventor(s) to the Assignee is attached hereto. This Assignment represents the entire chain of title of this invention from the Inventors to the Assignee.

I declare that all statements made herein are true, and that all statements made upon information and belief are believed to be true, and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001, and that willful, false statements may jeopardize the validity of the application, or any patent issuing thereon.

App. No. : 10/078,243
Filed : February 14, 2002

The undersigned hereby revokes any previous powers of attorney in the subject application, and hereby appoints the registrants of Knobbe, Martens, Olson & Bear, LLP, 620 Newport Center Drive, Sixteenth Floor, Newport Beach, California 92660, Telephone (949) 760-0404, Customer No. 20,995, as its attorneys with full power of substitution and revocation to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected herewith. This appointment is to be to the exclusion of the inventor(s) and his attorney(s) in accordance with the provisions of 37 C.F.R. § 3.71.

Please use Customer No. 20,995 for all communications.

Institute of Microelectronics

Dated: 18th Feb 2002

By: KSP

Title: Director
Address: 11 Science Park Road
Singapore Science Park II
Singapore 117685

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Application No.: 10/078,243

Client Code: ALLENG4.001AUS

Filing Date: February 14, 2002

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ASSIGNMENT

WHEREAS, We, Vaidyanathan Kripesh, a citizen of India, residing at Blk 428, #10-434, Clementi Avenue 3, Singapore 120428, Mahadevan K. Iyer, a citizen of India, residing at Blk 723, #24-180, Clementi West Street 2, Singapore 120723, Thiam Beng Lim, a citizen of Singapore, residing at 46 Toh Crescent, Singapore 507957, have invented certain new and useful improvements in a **PROCESS OF FORMING METAL SURFACES COMPATIBLE WITH A WIRE BONDING AND SEMICONDUCTOR INTEGRATED CIRCUITS MANUFACTURED BY THE PROCESS** for which we have executed an application for Letters Patent in the United States, Application No. 10/078,243, February 14, 2002.

AND WHEREAS, Institute of Microelectronics (hereinafter "ASSIGNEE"), a Corporation, with its principal place of business at 11 Science Park Road, Singapore Science Park II, Singapore 117685, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application:

NOW, THEREFORE, in consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest therein and in, to and under the said improvements, and the said application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

IN TESTIMONY WHEREOF, Assignor intending to be legally bound has hereunto affixed its signature.

This 14th day of Feb., 2002

V. Kripesh
Signature of Vaidyanathan Kripesh

This 14th day of Feb., 2002

Mahadevan K. Iyer
Signature of Mahadevan K. Iyer

This 18th day of Feb., 2002

Thiam Beng Lim
Signature of Thiam Beng Lim